

As a below named inventor, I hereby declare that:

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled LOW DIELECTRIC CONSTANT MATERIAL FOR INTEGRATED CIRCUIT FABRICATION, the specification of which is attached hereto;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Inventor's signature *[Signature]*

Date 9/2/98

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